

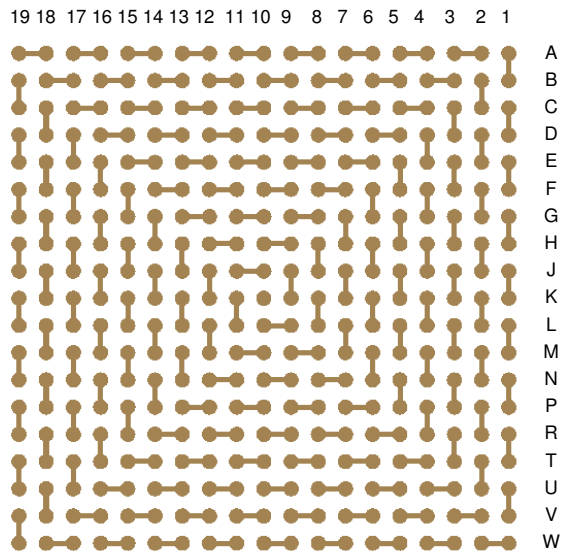
SECTION A-A

- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.45mm.
 - 4) SOLDER MASK DEFINED PAD OPENING: 0.36mm [14 MIL].
 - 5) PAD Cu DIAMETER: 0.508mm [20 MIL].
 - 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT).
 - 7) DUMMY DIE IS OPTIONAL.
 - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
 - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

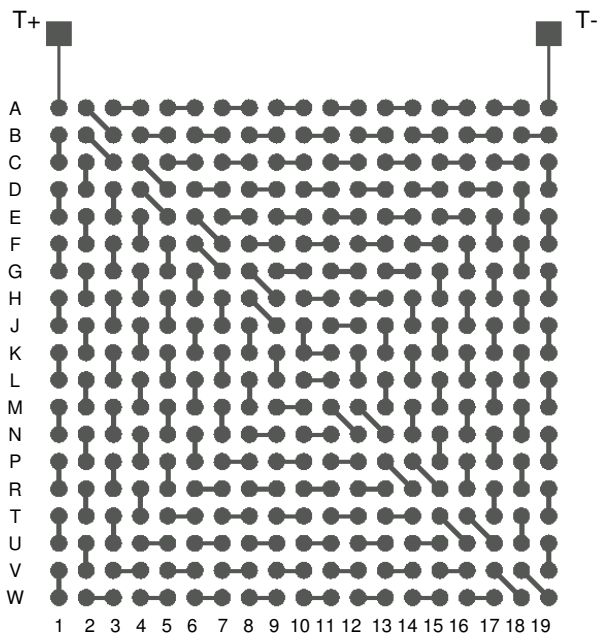
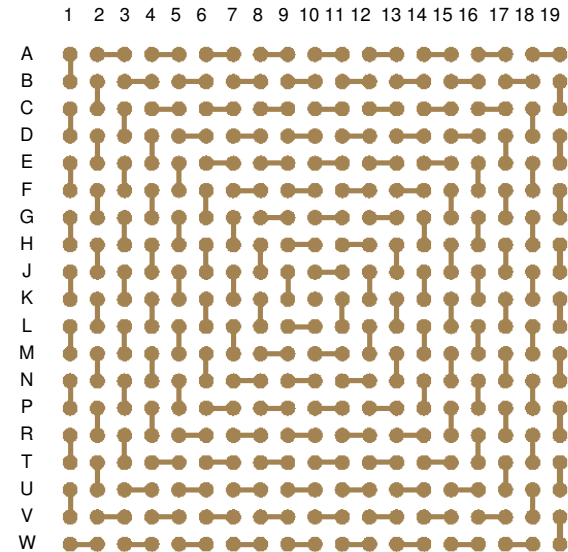
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA361T.8C-DC199D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA361T.8C1-DC199D	Sn96.5/Ag3.0/Cu0.5	SAC125	YES	YES
BGA361T.8-DC199D	Sn63/Pb37	Sn63	NO	YES

TOLERANCE UNLESS NOTED		APPROVALS		DATE						
X.X	+/- 0.3	DRAWN J. Hines		1/6/2012						
X.XX	+/- 0.03	ENG		MFG		TITLE BGA361T.8-DC199 DAISY CHAIN DUMMY				
X.XXX	+/- 0.003	THIRD ANGLE PROJECTION		SCALE 5.5:1		SIZE A		DRAWING NO. 581990		REV A
ALL DIMENSIONS IN <input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		REVISED		DO NOT SCALE DRAWING		SHEET 1 OF 2				

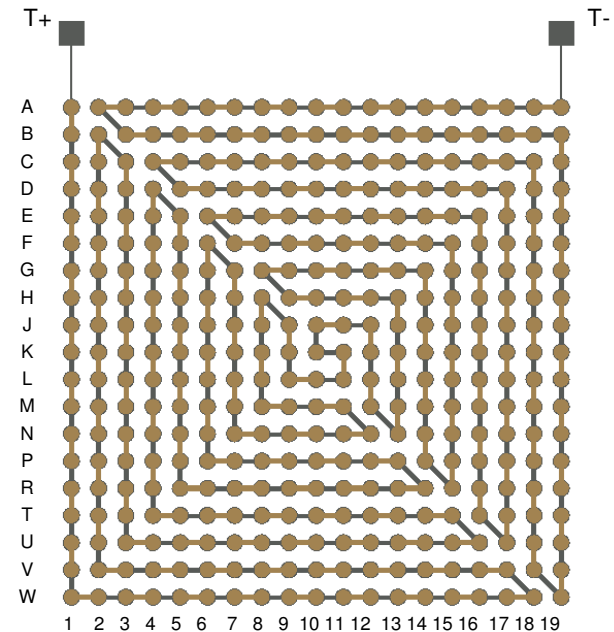
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.508mm [20 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm [6 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.36mm [14 MIL].

TopLine ®			
TITLE		BGA361T.8-DC199 DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
4.5:1	A	581990	A
DO NOT SCALE DRAWING			SHEET 2 OF 2